

3A, 200V - 600V Fast Recovery Surface Mount Rectifier

FEATURES

- Very low profile, typical height of 1.1mm
- Excellent high temperature stability
- Glass passivated chip junction
- Controlled avalanche characteristics
- Low leakage current
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

MECHANICAL DATA

- Case: TO-277A (SMPC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.095g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	3	Α	
V_{RRM}	200 - 600	V	
I _{FSM}	60 A		
T_{JMAX}	175 °C		
Package	TO-277A (SMPC)		
Configuration	Single die		

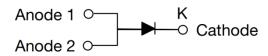








TO-277A (SMPC)



PARAMETER		SYMBOL	TPAR3D	TPAR3G	TPAR3J	UNIT
Marking code on the device			AR3D	AR3G	AR3J	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	V
Forward current		I _F	3		Α	
Surge peak forward current, 8.3ms single half sine wave superimposed on rated load		I _{FSM}	60		Α	
$I_{AS} = 2.5A$		L	20		mJ	
Non-repetitive avalanche energy	I _{AS} = 1.0A Typ	E _{AS}	30			mJ
Junction temperature		TJ	-55 to +175		°C	
Storage temperature		T _{STG}	-55 to +175		°C	

1



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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance ⁽¹⁾	$R_{\Theta JL}$	5.1	°C/W	
Junction-to-ambient thermal resistance ⁽²⁾	R _{OJA}	75	°C/W	

Notes:

- 1. Mounted on FR4 PCB with 16mm x 16mm Cu pad area
- 2. Free air, mounted on recommended pad

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_{F} = 3A, T_{J} = 25^{\circ}C$	1.20	1.55	V	
Forward voltage	I _F = 3A, T _J = 125°C	V _F	1.02	1.15	V
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C	· I _R	-	10	μΑ
	T _J = 125°C		-	250	μΑ
Junction capacitance	1MHz, V _R = 4.0V	C _J	58	-	pF
Reverse recovery time	IF = 0.5A, IR = 1.0A Irr = 0.25A	t _{rr}	-	120	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
TPAR3x	TO-277A (SMPC)	6,000 / Tape & Reel

Notes:

1. "x" defines voltage from 200V(TPAR3D) to 600V(TPAR3J)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

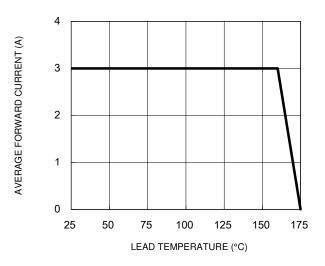


Fig.3 Typical Reverse Characteristics

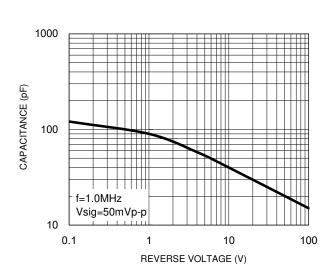
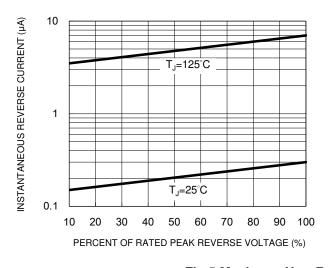


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



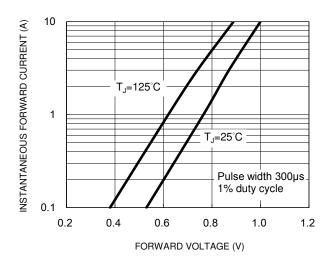
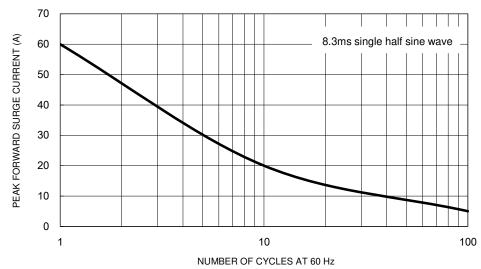


Fig.5 Maximum Non-Repetitive Forward Surge Current



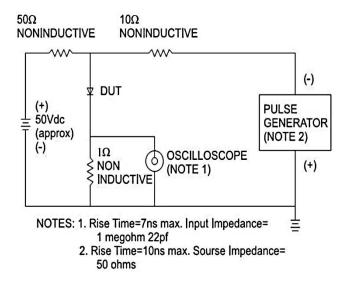
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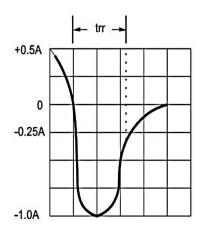


CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

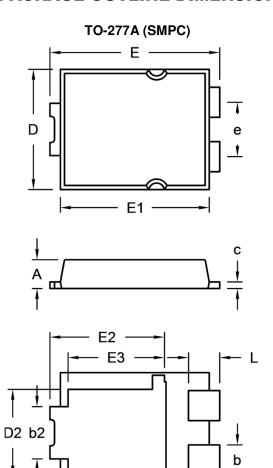
Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram





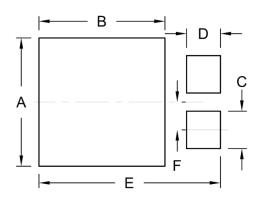


PACKAGE OUTLINE DIMENSIONS



DIM.	M. Unit (mm) Min. Max.		Unit ((inch)
			Min.	Max.
А	1.000	1.200	0.039	0.047
b	1.000	1.300	0.039	0.051
b2	1.850	2.150	0.073	0.085
С	0.175	0.325	0.007	0.013
D	4.550	4.650	0.179	0.183
D2	3.170	3.470	0.125	0.137
E	6.350	6.650	0.250	0.262
E1	5.650	5.750	0.222	0.226
E2	4.235	4.535	0.167	0.179
E3	3.540	3.840	0.139	0.151
е	1.930	2.230	0.076	0.088
L	1.043	1.343	0.041	0.053

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	4.80	0.189
В	4.72	0.186
С	1.40	0.055
D	1.27	0.050
E	6.80	0.268
F	1.04	0.041

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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